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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/511,557	05/26/2005	Dietrich Mund	2133.062USU	4190
27623 OHLANDT. G	7590 06/28/2007 REELEY, RUGGIERO &	EXAMINER		
ONE LANDMARK SQUARE, 10TH FLOOR STAMFORD, CT 06901			WILCZEWSKI, MARY A	
			ART UNIT	PAPER NUMBER
	,		2822	
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	•		06/28/2007	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

		Application No.	Applicant(s)
		10/511,557	MUND ET AL.
Office Action Summary		Examiner	Art Unit
		M. Wilczewski	2822
D. J. J.C.	The MAILING DATE of this communication app		vith the correspondence address
WHI(- Exte after - If NO - Failt Any	IORTENED STATUTORY PERIOD FOR REPLY CHEVER IS LONGER, FROM THE MAILING DA resions of time may be available under the provisions of 37 CFR 1.13 resiX (6) MONTHS from the mailing date of this communication. Depriod for reply is specified above, the maximum statutory period varieto reply within the set or extended period for reply will, by statute reply received by the Office later than three months after the mailing lated patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUN 36(a). In no event, however, may a will apply and will expire SIX (6) MC, cause the application to become a	ICATION. a reply be timely filed ONTHS from the mailing date of this communication. ABANDONED (35 U.S.C. § 133).
Status			
2a)☐	Responsive to communication(s) filed on <u>15 O</u> This action is FINAL . 2b) This Since this application is in condition for allowar closed in accordance with the practice under E	action is non-final.	•
Disposit	tion of Claims		
5)□ 6)⊠ 7)□	Claim(s) 1-3,5-34 and 37-40 is/are pending in 4a) Of the above claim(s) is/are withdray Claim(s) is/are allowed. Claim(s) 1-3,5-34 and 37-40 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction and/or	wn from consideration.	
Applicat	tion Papers		
10)⊠	The specification is objected to by the Examine The drawing(s) filed on <u>15 October 2004</u> is/are Applicant may not request that any objection to the Replacement drawing sheet(s) including the correct The oath or declaration is objected to by the Ex	: a)⊠ accepted or b)□ drawing(s) be held in abey tion is required if the drawir	ance. See 37 CFR 1.85(a). ng(s) is objected to. See 37 CFR 1.121(d).
Priority	under 35 U.S.C. § 119		
a	Acknowledgment is made of a claim for foreign All b Some * c None of: 1.	ts have been received. ts have been received in brity documents have been u (PCT Rule 17.2(a)).	Application No en received in this National Stage
Attachme	nt(s)		
2) Noti 3) Info	ice of References Cited (PTO-892) ice of Draftsperson's Patent Drawing Review (PTO-948) irmation Disclosure Statement(s) (PTO/SB/08) ier No(s)/Mail Date 15 October 2004; 20 June 2005.	Paper N	v Summary (PTO-413) o(s)/Mail Date f Informal Patent Application

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DETAILED ACTION

This Office action is in response to the Preliminary Amendment filed on October 15, 2004. Claims 1-3, 5-34, and 37-40 are pending in the application.

Priority

Receipt is acknowledged of papers submitted under 35 U.S.C. 119(a)-(d), which papers have been placed of record in the file.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 39 is rejected under 35 U.S.C. 102(b) as being clearly anticipated by Kobori et al., EP 0 280 905.

Kobori et al. disclose a process for joining at least two silicon substrates to manufacture pressure sensor units by providing a first substrate (10); producing a plurality of nested frame joining elements (32) on a first surface of the first substrate; providing a second substrate (12); and joining the first and second substrates by the plurality of nested frame joining, see column 4, lines 25-58, column 5, line 5, bridging column 6 to line 32, and figures 1-7.

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Claims 40 is rejected under 35 U.S.C. 102(b) as being clearly anticipated by Kobori et al., EP 0 280 905.

Kobori et al. disclose a composite element including pressure sensor units comprising a first substrate (10); a joining elements (32) on a first surface of the first substrate; a second substrate (12), the first and second substrates being joined by the joining element; and a plurality of nested frames being provided as the joining element, see figures 1-7.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-3, 5-18 and 37 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kobori et al., EP 0 280 905, cited by Applicants.

Kobori et al. disclose a process for joining at least two silicon substrates to manufacture pressure sensor units by providing a first substrate (10); producing a joining element (32) in the form of a frame on a first surface of the first substrate, the frame made of a binary system of materials or glass (a borosilicate glass); providing a second substrate (12); and joining the first and second substrates by the joining element by anodic bonding, see column 4, lines 25-58, column 5, line 5, bridging column 6 to line 32, and figures 1-7. Kobori et al. disclose that after joining the bonded wafers are

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diced, see column 7, lines 3-22. Kobori et al. disclose the process used to form the joining element in figures 8(a)-8(g). Formation of photoresist layer 64 shown in figure 8(c) is deemed to planarize one surface of the joining element, since after formation of resist 64 the surface of substrate 10 on which the borosilicate glass 32 is formed is made planar or flat. As shown in figure 1, the joining element 32 comprises a plurality of nested frames.

Kobori et al. teaches that the borosilicate glass that comprises the joining element is formed by sputtering (column 4, lines 47-51). Kobori et al. lack anticipation only of forming the borosilicate glass by evaporation. Choi et al. disclose a method of anodically bonding two silicon wafer using a borosilicate glass formed by evaporation, see the abstract. Choi et al. disclose that the evaporation coating of borosilicate glass permits high deposition rates with very little surface roughness, and further disclose that a borosilicate glass formed by evaporation has high bonding strength, therefore, it would have been obvious to one skilled in the art to form the borosilicate glass joining element formed in the known method of Kobori et al. by evaporation coating.

Claims 19-34 and 38 are rejected under 35 U.S.C. 102(b) as anticipated by or, in the alternative, under 35 U.S.C. 103(a) as obvious over Kobori et al., EP 0 280 905.

Kobori et al. disclose a composite element including pressure sensor units comprising a first substrate (10); a joining element (32) on a first surface of the first substrate, the joining element being a frame made of a binary system of materials or glass (borosilicate glass); a second substrate (12), wherein the first and second

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substrates are joined or bonded by the joining element so that a cavity is formed between the first and second substrates; see figures 1-7.

Independent claims 19 and 34, and 38, recite that the glass layer is applied by evaporation coating. Kobori et al. teach to form the borosilicate glass by sputtering (column 4, lines 47-51). However, the present claims are product claims, Applicants have merely chosen to define the claimed product by the process by which it was made. Kobori et al. teach a product that appears to be the same as, or an obvious variant of, the product set forth in the product-by-process claims of the instant application although produced by a different process. See In re Marosi, 218 USPQ 289 (Fed. Cir. 1983); In re Thorpe, 227 USPQ 964 (Fed. Cir. 1985); and In re Brown 173 USPQ 685, 688 (CCPA 1972). It has been well established that process limitations cannot impart. patentability to an old/obvious product. Process limitations in a product claim are only significant to the extent that they distinguish the claimed product over the prior art product. Once a product appearing to be substantially identical is found a 35 U.S.C. 102 /103 rejection is made, the burden shifts to the Applicants to show an unobvious difference between the claimed product and that of the prior art. Once the examiner provides a rationale tending to show that the claimed product appears to be the same or similar to that of the prior art, although produced by a different process, the burden shifts to applicant to come forward with evidence establishing an unobvious difference between the claimed product and the prior art product. In re Marosi, 218 USPQ 289, 292 (Fed. Cir. 1983).

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Claim 9 is rejected under 35 U.S.C. 103(a) as being unpatentable over Kobori et al., EP 0 280 905, as applied to claim 1 above, and further in view of Black et al., US Patent 4,426,768.

Kobori et al. is applied as above. Kobori et al. disclose the photolithographic patterning of borosilicate glass 32, see figures 8(c)-8(e) and column 7, lines 41-52. However, it is known to use a lift-off technique to pattern borosilicate glass layers in the fabrication of pressure sensors, see Black et al., figure 6 and column 4, lines 17-41. It would have been obvious to one skilled in the art that the lift-off technique taught by Black et al. could have been substituted for the photolithographic patterning step of Kobori et al., since the prior art teaches the functional equivalence of the two techniques to pattern borosilicate glass layers in pressure sensors.

Conclusion

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. The additionally cited references disclose the bonding of at least two substrates to form a cavity therebetween.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to M. Wilczewski whose telephone number is (571) 272-1849. The examiner can normally be reached on Monday-Thursday.

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If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Zandra Smith can be reached on 571-272-2429. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

M. Wilczewski Primary Examiner Tech Center 2800